

NP35N04YLG

MOS FIELD EFFECT TRANSISTOR

R07DS0182EJ0100 Rev.1.00 Oct 22, 2010

Description

The NP35N04YLG is N-channel MOS Field Effect Transistor designed for high current switching applications.

Features

- Low on-state resistance
 - --- $R_{DS(on)}$ = 9.7 mΩ MAX. (V_{GS} = 10 V, I_D = 17.5 A)
 - --- $R_{DS(on)}$ = 15 mΩ MAX. (V_{GS} = 5 V, I_D = 17.5 A)
- Logic level drive type
- Gate to Source ESD protection diode built in
- Designed for automotive application and AEC-Q101 qualified

Ordering Information

| Part No. | LEAD PLATING | PACKING | Package |
|----------------------|---------------|------------------|------------------------------|
| NP35N04YLG -E1-AY *1 | Pure Sn (Tin) | Tape 2500 p/reel | 8-pin HSON, Taping (E1 type) |
| NP35N04YLG -E2-AY *1 | | | 8-pin HSON, Taping (E2 type) |

Note: *1. Pb-free (This product does not contain Pb in the external electrode.)

Absolute Maximum Ratings $(T_A = 25^{\circ}C)$

| Item | Symbol | Ratings | Unit |
|--|-----------------------|-------------|------|
| Drain to Source Voltage (V _{GS} = 0 V) | V _{DSS} | 40 | V |
| Gate to Source Voltage (V _{DS} = 0 V) | V _{GSS} | ±20 | V |
| Drain Current (DC) (T _C = 25°C) | I _{D(DC)} | ±35 | A |
| Drain Current (pulse) *1 | I _{D(pulse)} | ±105 | A |
| Total Power Dissipation (T _C = 25°C) | P _{T1} | 77 | W |
| Total Power Dissipation (T _A = 25°C) *2 | P _{T2} | 1.0 | W |
| Channel Temperature | T _{ch} | 175 | °C |
| Storage Temperature | T _{stg} | -55 to +175 | °C |
| Repetitive Avalanche Current *3 | I _{AR} | 22 | A |
| Repetitive Avalanche Energy *3 | E _{AR} | 48 | mJ |

Thermal Resistance

Channel to Case Thermal Resistance $R_{th(ch-C)}$ 1.95 °C/W Channel to Ambient Thermal Resistance *2 $R_{th(ch-A)}$ 150 °C/W

Notes: *1. $T_C = 25^{\circ}C$, $PW \le 10 \mu s$, Duty Cycle $\le 1\%$

*2. Mounted on glass epoxy substrate of 40 mm x 40 mm x 0.8 mmt

*3. $T_{ch(peak)} \le 150^{\circ}C$, $R_G = 25 \Omega$

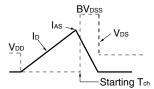
Electrical Characteristics (T_A = 25°C)

| Item | Symbol | Min | Тур | Max | Unit | Test Conditions |
|---|----------------------|-----|------|------|------|---|
| Zero Gate Voltage Drain Current | I _{DSS} | | | 1 | μA | $V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$ |
| Gate Leakage Current | I _{GSS} | | | ±10 | μA | $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ |
| Gate to Source Threshold Voltage | $V_{GS(th)}$ | 1.4 | 1.9 | 2.5 | V | $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ |
| Forward Transfer Admittance *1 | y _{fs} | 15 | 30 | | S | $V_{DS} = 5 \text{ V}, I_{D} = 17.5 \text{ A}$ |
| Drain to Source On-state Resistance *1 | R _{DS(on)1} | | 7.8 | 9.7 | mΩ | V _{GS} = 10 V, I _D = 17.5 A |
| Drain to Source On-state Resistance *1 | R _{DS(on)2} | | 9.6 | 15 | mΩ | $V_{GS} = 5 \text{ V}, I_D = 17.5 \text{ A}$ |
| Input Capacitance | C _{iss} | | 1900 | 2850 | pF | $V_{DS} = 25 V$, |
| Output Capacitance | Coss | | 190 | 290 | pF | $V_{GS} = 0 V$, |
| Reverse Transfer Capacitance | C _{rss} | | 120 | 220 | pF | f = 1 MHz |
| Turn-on Delay Time | t _{d(on)} | | 13 | 26 | ns | $V_{DD} = 20 \text{ V}, I_D = 17.5 \text{ A},$ |
| Rise Time | t _r | | 11 | 27 | ns | $V_{GS} = 10 V,$ |
| Turn-off Delay Time | $t_{d(off)}$ | | 43 | 86 | ns | $R_G = 0 \Omega$ |
| Fall Time | t _f | | 5 | 12 | ns | |
| Total Gate Charge | Q_G | | 34 | 51 | nC | $V_{DD} = 32 \text{ V},$ |
| Gate to Source Charge | Q_{GS} | | 6 | | nC | V_{GS} = 10 V , |
| Gate to Drain Charge | Q_{GD} | | 10 | | nC | I _D = 35 A |
| Body Diode Forward Voltage *1 | $V_{F(S-D)}$ | | 0.91 | 1.5 | V | I _F = 35 A, V _{GS} = 0 V |
| Reverse Recovery Time | t _{rr} | | 27 | | ns | $I_F = 35 \text{ A}, V_{GS} = 0 \text{ V},$ |
| Reverse Recovery Charge | Q _{rr} | | 25 | | nC | di/dt = 100 A/μs |

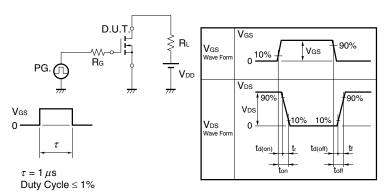
Note: *1. Pulsed

TEST CIRCUIT 1 AVALANCHE CAPABILITY

$V_{GS} = 20 \rightarrow 0 \text{ V}$ $PG. \bigcirc PG. \bigcirc PG.$



TEST CIRCUIT 2 SWITCHING TIME

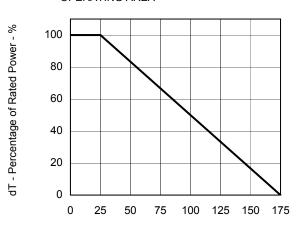


TEST CIRCUIT 3 GATE CHARGE

$$\begin{array}{c|c} D.U.T. \\ \hline I_G = 2 \underset{W}{\text{MA}} \\ \hline PG. \\ \hline \end{array} \begin{array}{c} D.U.T. \\ \hline \\ \hline \\ \hline \end{array} \begin{array}{c} \\ \\ \hline \\ \hline \end{array} \begin{array}{c} \\ \\ \hline \\ \hline \end{array} \begin{array}{c} \\ \\ \\ \\ \hline \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\$$

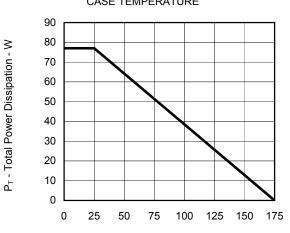
Typical Characteristics ($T_A = 25^{\circ}C$)

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



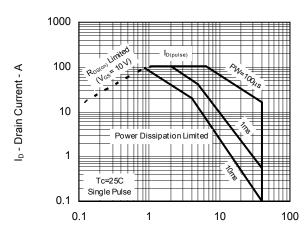
T_C - Case Temperature - °C

TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



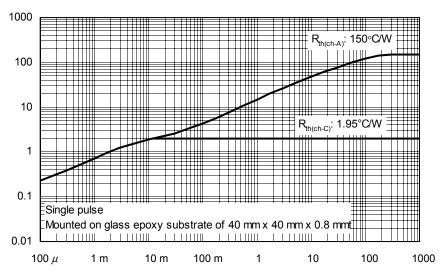
T_C - Case Temperature - °C

FORWARD BIAS SAFE OPERATING AREA



 V_{DS} - Drain to Source Voltage - V

TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



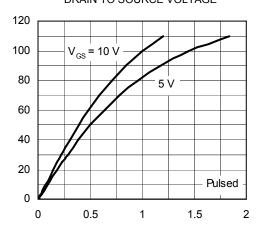
PW - Pulse Width - s

I_D - Drain Current - A

V_{GS(th)} - Gate to Source Threshold Voltage - V

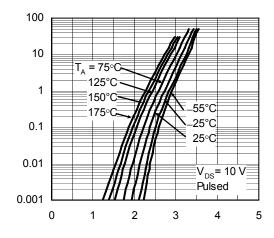
 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain to Source On-state Resistance - $m\Omega$

DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



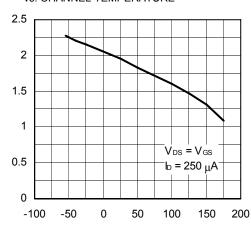
 V_{DS} - Drain to Source Voltage - V

FORWARD TRANSFER CHARACTERISTICS



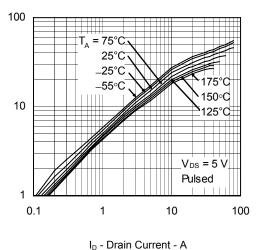
V_{GS} - Gate to Source Voltage - V

GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE

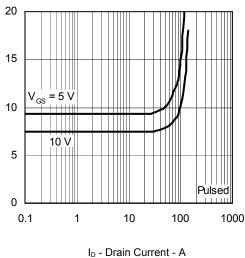


T_{ch} - Channel Temperature - °C

FORWARD TRANSFER ADMITTANCE vs. DRAIN **CURRENT**



DRAIN TO SOURCE ON-STATE RESISTANCE vs. **DRAIN CURRENT**

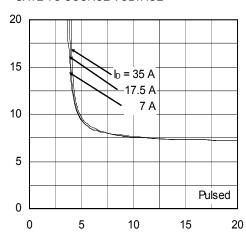




Ip - Drain Current - A

| y_{fs} | - Forward Transfer Admittance - S

DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



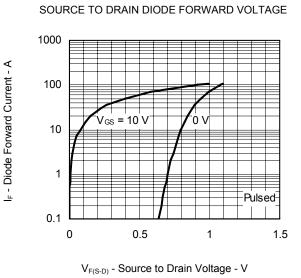
V_{GS} - Gate to Source Voltage - V

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - Drain to Source On-state Resistance - $m\Omega$

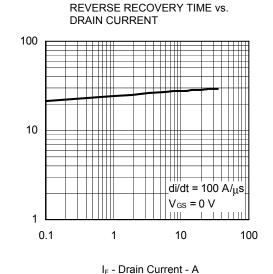
t_{d(on)}, t_r, t_{d(off)}, t_f - Switching Time - ns

DRAIN TO SOURCE ON-STATE RESISTANCE vs. CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE CHANNEL TEMPERATURE 10000 25 $I_D = 17.5 A$ Ciss, Coss, Crss - Capacitance - pF Pulsed 20 $V_{GS} = 5 V$ 1000 15 10 V 10 100 5 $V_{GS} = 0 V_{-}$ f = 1MHz10 0 10 -50 0.1 -100 0 50 100 150 200 V_{DS} - Drain to Source Voltage - V T_{ch} - Channel Temperature - °C SWITCHING CHARACTERISTICS DYNAMIC INPUT/OUTPUT CHARACTERISTICS 1000 40 V_{DD} = 20 V V_{DS} - Drain to Source Voltage - V V_{GS} = 10 V 35 $R_G = 0 \Omega$ $V_{DD} = 32 \text{ V}$ 30 100 25 t_{d(off} 20 15 10 10 5 0 1 0 10 20 30 0.1 10 100

Q_G - Gate Charge - nC



I_D - Drain Current - A



100

12

10

8

6

4

2

0

40

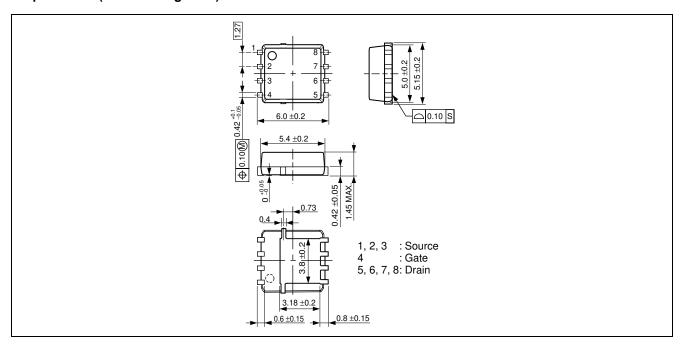
V_{GS} - Gate to Source Voltage - V

lo = 35 A

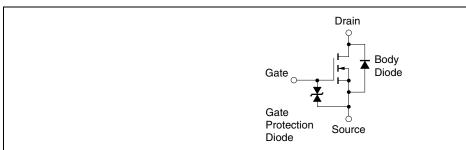
t_{rr} - Reverse Recovery Time - ns

Package Drawings (Unit: mm)

8-pin HSON (Mass: 0.13 g TYP.)



Equivalent Circuit



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

Revision History NP35N04YLG

| | | Description | | |
|------|--------------|--------------|----------------------|--|
| Rev. | Date | Page Summary | | |
| 1.00 | Oct 22, 2010 | - | First Edition Issued | |
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